



NT66P13

OTP 4-bit Microcontroller with LCD Driver

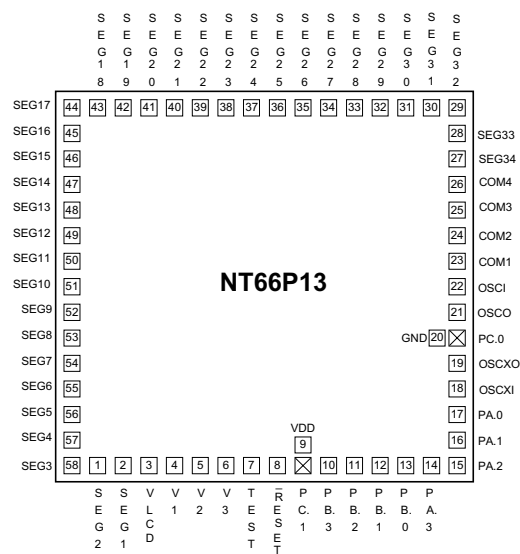
Features

- NT6610C-based single-chip 4-bit micro-controller
- ROM: 4096x 16 bits
- RAM: 512x 4 bits (System & Data memory)
- Operation voltage: 2.5V - 6.0V
- 8 CMOS bi-directional I/O pins
- 4-Level subroutine nesting (include interrupts)
- One 8-bit auto re-load timer/counter
- 8-bit Base timer
- Powerful interrupt sources:
 - External interrupts ($\overline{\text{INT0}}$).
 - Internal interrupt (Timer0).
 - Internal interrupt (Base Timer).
 - Port's falling edge interrupt: PORTB ($\overline{\text{INT1}}$)
- LCD driver: 136 dots(1/4 duty 1/3 bias)
- LCD used as scan output
- Built-in dual tone PSG with one noise generator
- 2 Clock source
 - OSC: (code option)
 - Crystal oscillator 32.768K
 - RC oscillator: 262K
 - OSCX: (system register select)
 - Ceramic oscillator 455K
 - RC oscillator 1.8M or 2M
- Instruction cycle time:
 - 122.07 μ s for 32.768 KHz crystal
 - 15.27 μ s for 262 KHz RC
 - 8.79 μ s for 455KHz ceramic
 - 2.22 μ s for 1.8 MHz RC
 - 2 μ s for 2.0 MHz RC
- Two low power operation mode: HALT and STOP
- Low power consumption
- Warm up timer for power on reset

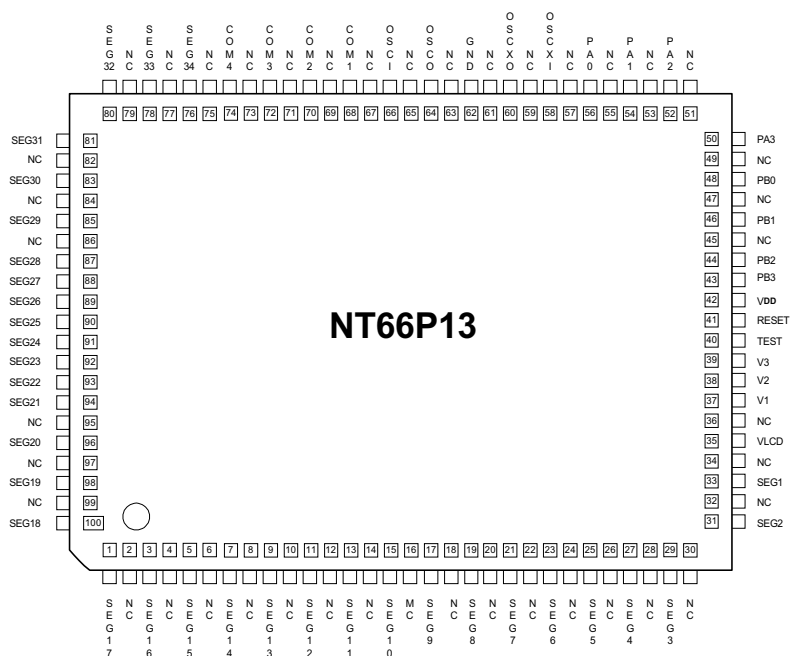
General Description

NT66P13 is a single chip microcontroller integrated with SRAM, OTP ROM, Timer and Dual-tone PSG, LCD driver and I/O port. This chip builds in a dual-oscillator to enhance the total chip performance.

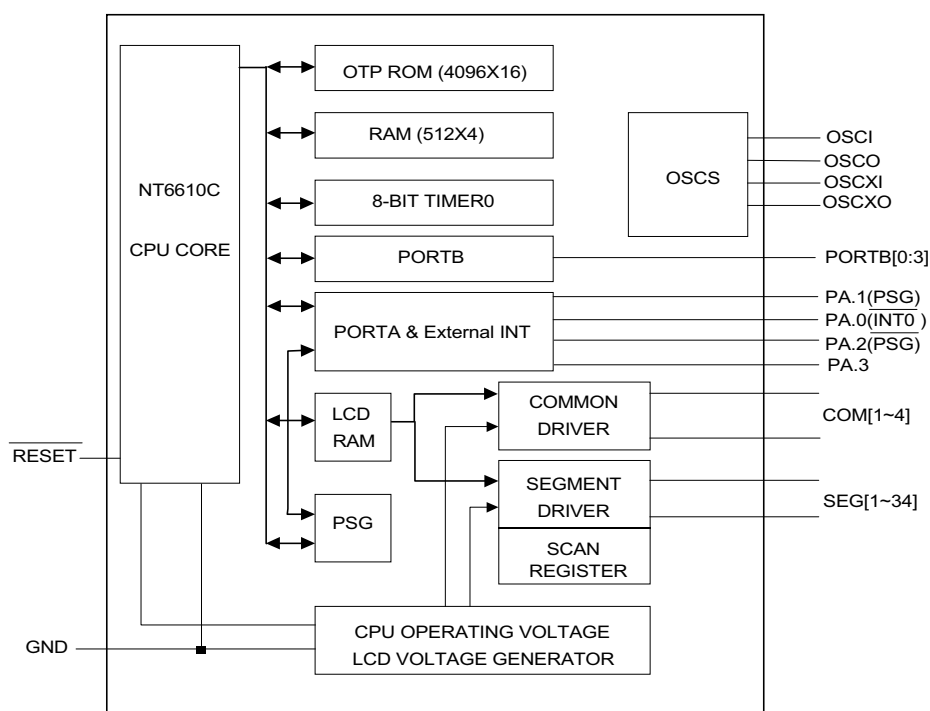
Pad Configuration



Pin Configuration



Block Diagram



Pad Description

Pad No.	Designation	I/O	Description
1,2,31~58	SEG1~SEG30	O	Segment signal output for LCD display; Shares with scan output.
3~6	VLcd,V1,V2,V3	I	Connect with external LCD divided resistance
7	TEST	I	Test pin (Internal pull-low). No connect for user.
8	RESET	I	Reset input(No internal pull-up)
9	VDD	P	Power supply.
10~13	Port B.3~Port B.0	I/O	Bit programmable I/O ,Vector interrupt($\overline{INT1}$)
14~17	Port A.3~Port A.0	I/O	Bit programmable I/O,PA.0 shared with $\overline{INT0}$ PA.1 , PA.2shared with PSG output
18	OSCXI	I	Oscillator X input pin
19	OSCXO	O	Oscillator X output pin
20	GND	P	Ground pin
21	OSCO	O	Oscillator output pin
22	OSCI	I	Oscillator input pin
23~26	COM1~COM4	O	Common signal output for LCD display
27~30	SEG34~SEG31	O	segment signal output for LCD display

Pin Description

PIN No.	Designation	I/O	Description
1,3,5,7,9,11,13, 15,17,19,21,23, 25,27,29,31,33	SEG17~SEG1	O	Segment signal output for LCD display; share with scan output.
83,85,87~94,96, 98,100	SEG30~SEG18	O	Segment signal output for LCD display; share with scan output.
35,37~39	VLcd,V1,V2,V3	I	Connect with external LCD divided resistance
40	TEST	I	Test pin (Internal pull-low). No connect for user.
41	RESET	I	Reset input(No internal pull-up)
42	VDD	P	Power supply.
43,44,46,48	Port B.3~Port B.0	I/O	Bit programmable I/O ,Vector interrupt($\overline{INT1}$)
50,52,54,56	Port A.3~Port A.0	I/O	Bit programmable I/O,PA.0 shared with $\overline{INT0}$ PA.1 , PA.2 shared with PSG output
58	OSCXI	I	Oscillator X input pin
60	OSCXO	O	Oscillator X output pin
62	GND	P	Ground pin
64	OSCO	O	Oscillator output pin
66	OSCI	I	Oscillator input pin
68,70,72,74	COM1~COM4	O	Common signal output for LCD display
76,78,80,81	SEG34~SEG31	O	segment signal output for LCD display

Functional Description

1. CPU

The CPU contains the following function blocks: Program Counter, Arithmetic Logic Unit (ALU), Carry Flag, Accumulator, Table Branch Register, Data Pointer (INX, DPH, DPM, and DPL), and Stack.

(a) PC (Program Counter)

The Program Counter is used to address the 4K program ROM. It consists of 12-bits: Page Register (PC11), and Ripple Carry Counter (PC10, PC9, PC8, PC7, PC6, PC5, PC4, PC3, PC2, PC1, PC0).

The program counter normally increases by one (+1) with every execution of an instruction except in the following cases:

- 1) When executing a jump instruction (such as JMP, BA0, BAC);
- 2) When executing a subroutine call instruction (CALL);
- 3) When an interrupt occurs;
- 4) When the chip is at the INITIAL RESET mode.

The program counter is loaded with data corresponding to each instruction.

The unconditional jump instruction (JMP) can be set at 1-bit page register for higher than 2K.

(b) ALU and CY

ALU performs arithmetic and logic operations. The ALU provides the following functions:
Binary addition/subtraction (ADC, SBC, ADD, SUB, ADI, SBI)

Decimal adjustment for addition/subtraction (DAA, DAS)
Logic operations (AND, EOR, OR, ANDIM, EORIM, ORIM)
Decision (BA0, BA1, BA2, BA3, BAZ, BAC)
Logic Shift (SHR)

The Carry Flag (CY) holds the ALU overflow, which the arithmetic operation generates. During an interrupt service or call instruction, the carry flag is pushed into the stack and restored back from the stack by the RTNI instruction. It is unaffected by the RTNW instruction.

(c) Accumulator

Accumulator is a 4-bit register holding the results of the arithmetic logic unit. In conjunction with ALU, data transfers between the accumulator and system register, LCD RAM, or data memory can be performed.

(d) Stack

A group of registers used to save the contents of CY & PC (10-0) sequentially with each subroutine call or interrupt. It is organized 13 bits X 4 levels. The MSB is saved for CY. 4 levels are the maximum allowed for subroutine calls and interrupts.

The contents of Stack are returned sequentially to the PC with the return instructions (RTNI/RTNW). Stack is operated on a first-in, last-out basis. This 4-level nesting includes both subroutine calls and interrupts requests. Note that program execution may enter an abnormal state if the number of calls and interrupt requests exceeds 4, and the bottom of stack will be shifted out.

2. ROM

The ROM can address 4096 words × 16 bits of program area from \$000 to \$FFF.

(a) Vector Address Area (\$000 to \$004)

The program is sequentially executed. There is an area address \$000 through \$004 that is reserved for a special interrupt service routine such as starting vector address.

Address	Instruction	Function
\$000H	JMP Instruction	Jump to RESET service routine
\$001H	JMP Instruction	Jump to $\overline{\text{INT0}}$ service routine
\$002H	JMP Instruction	Jump to Timer0 service routine
\$003H	JMP Instruction	Jump to Base Timer service routine
\$004H	JMP Instruction	Jump to $\overline{\text{INT1}}$ service routine

(b) Table Data Reference

Table Data can be stored in program memory and can be referenced by using Table Branch (TJMP) and Return Constant (RTNW) instructions. The Table Branch Register (TBR) and Accumulator (AC) is placed by an offset address in program ROM. TJMP instruction branch into address $((\text{PC11} - \text{PC8}) \times (2^8) + (\text{TBR}, \text{AC}))$. The address is determined by RTNW to return look-up value into (TBR, AC). ROM code bit7-bit4 is placed into TBR and bit3-bit0 into AC.

3. RAM

Built-in SRAM contains general-purpose data memory, LCD RAM, and system registers. They can be direct accessed by in one instruction cycle. Because of its static nature, the RAM can keep data after the CPU enters STOP or HALT.

(a)Data memory, LCD RAM, and System register

The following is the memory allocation map:

\$000~\$01F: System register and I/O

\$020~\$1FF: Data memory (480×4bits, divided into 4 banks).

\$300~\$321, \$328~\$345, \$350~\$36D: LCD RAM space (34×4 bits).

(b)Data Pointer

The Data Pointer can indirectly address data memory. Pointer address is located in register DPM (3-bits) and DPL (4-bits). The addressing range can have 128 locations. Pseudo index address (INX) is used to read or write Data memory, and then RAM address bit9-bit0 comes from DPH, DPM and DPL.

(c)Configuration of System Register

Address	Bit3	Bit2	Bit1	Bit0	Function	Initial Value	R/W
\$00	IEX	IET0	IEBT	IEP	Interrupt enable flags	0000	R/W
\$01	IRQX	IRQT0	IRQBT	IRQP	Interrupt request flags	0000	R/W
\$02	TM0.3	TM0.2	TM0.1	TM0.0	Timer0 mode register	0000	R/W
\$03	BTM.3	BTM.2	BTM.1	BTM.0	Base timer mode register	0000	R/W
\$04	TOL.3	TOL.2	TOL.1	TOL.0	Timer0 load/counter low nibble	0000	R/W
\$05	TOH.3	TOH.2	TOH.1	TOH.0	Timer0 load/counter high nibble	0000	R/W
\$06~\$07	-	-	-	-	Reserved	-	-
\$08	PA.3	PA.2	PA.1	PA.0	PORTA	0000	R/W
\$09	PB.3	PB.2	PB.1	PB.0	PORTB	0000	R/W
\$0A	-	-	PC.1	PC.0	Bonding option	01(default)	R
\$0B	PACR.3	PACR.2	PACR.1	PACR.0	Set PORTA to be output port	0000	W
\$0C	PBCR.3	PBCR.2	PBCR.1	PBCR.0	Set PORTB to be output port	0000	W
\$0D	LPD3	LPD2	LPD1	LPD0	LPD Enable Control (LPD3~0): 0101: LPD Enable (Default); 1010: LPD Disable	0101	W
\$0E	TBR.3	TBR.2	TBR.1	TBR.0	Table branch register	0000	R/W
\$0F	INX.3	INX.2	INX1	INX.0	Index register(INX)	0000	R/W
\$10	DPL3	DPL2	DPL1	DPL0	Data pointer for INX low nibble	0000	R/W
\$11	-	DPM.2	DPM.1	DPM.0	Data pointer for INX middle nibble	0000	R/W
\$12	-	DPH.2	DPH.1	DPH.0	Data pointer for INX high nibble	0000	R/W
\$13	PPULL	PAM2	PAM1	HLM	Bit1,2:PA.1 & PA.2 as PSG output or I/O PORT Bit0:Heavy load mode Bit3:Port pull-up control	0000	R/W
\$14	OXS	-	OXM	OXON	Bit0:Turn on OSCX oscillator Bit1:CPU clocks select (1:OSCX/0:OSC) Bit3:OSCX type selection	0000	R/W
\$15	LPS1	LPS0	LCDOFF	Should be set "1"	Bit0:should be set "1" Bit1:LCD off Bit2,3:LCD frequency control	0000	R/W
\$16	LPD	O/S	-	-	Bit2:Set LCD segment as output Bit3:LCD Power degrade	0000	R/W
\$17	C1.3	C1.2	C1.1	C1.0	PSG channel 1 low nibble	0000	W
\$18	OCT1	C1.6	C1.5	C1.4	PSG channel 1high nibble Bit3:channel 1 octave shift control	0000	W
\$19	C2.3	C2.2	C2.1	C2.0	PSG channel 2 nibble 1 or alarm output	0000	W
\$1A	C2.7	C2.6	C2.5	C2.4	PSG channel 2 nibble 2	0000	W

\$1B	C2.11	C2.10	C2.9	C2.8	PSG channel 2 nibble 3	0000	W
\$1C	OCT2	C2.14	C2.13	C2.12	PSG channel 2 nibble 4 Bit3:channel 2 octave shift control	0000	W
\$1D	VOL1	VOL0	CH2EN	CH1EN	Bit0,Bit1:Channel 1,2 enable Bit2,Bit3:volume control	0000	W
\$1E	SEL1	SEL0	C2M	C1M	Bit0,1:PSG1,PSG2 mode control Bit2,3:PSG1,PSG2 clock source selection	0000	W
\$1F	-	-	-	-	Reserved	-	-

4. Oscillator circuit

(a) Circuit Configuration

NT66P13 has two on-chip oscillation circuits OSC and OSCX.

OSC is a low frequency crystal (Typ. 32.768KHz) or RC (Typ. 262KHz) determined by the code option. This is designed for low frequency operation. OSCX also has two types: ceramic (Typ. 455KHz) or RC (1.8M or 2MHz) to determine by software option. It is designed for high frequency operation.

It is possible to select the high speed CPU processing by a high frequency clock and select low power operation by low operation clock. At starting of reset initialization, OSC starts oscillation and OSCX is turned off. Immediate after reset initialization, the OSC clock is automatically selected as the system clock input source.

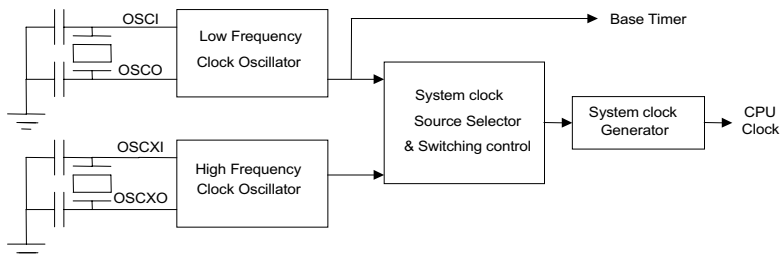


Figure 1 Oscillator Block Diagram

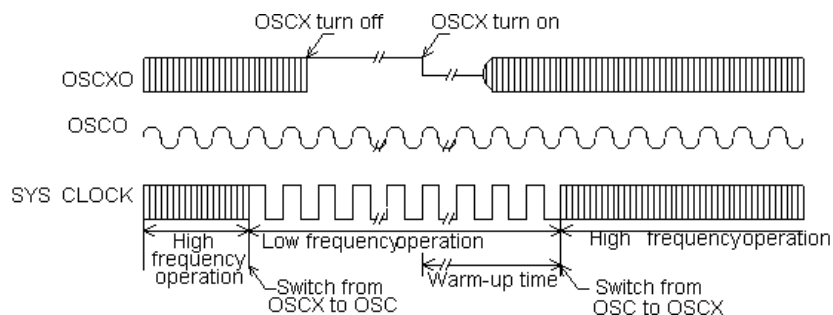
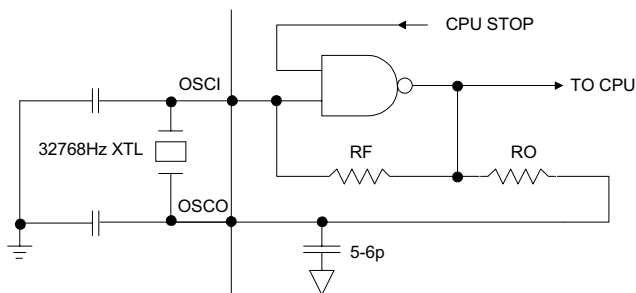


Figure 2 Timing of system Clock Switching

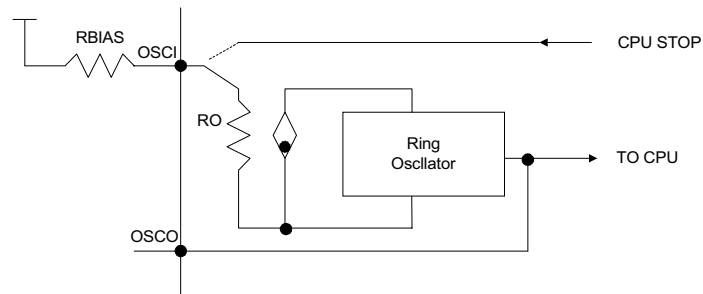
(b) OSC oscillation

The OSC generates the basic clock pulses that provide the CPU and peripherals (Timer0, LCD) with an operating clock.

OSC Crystal oscillator type

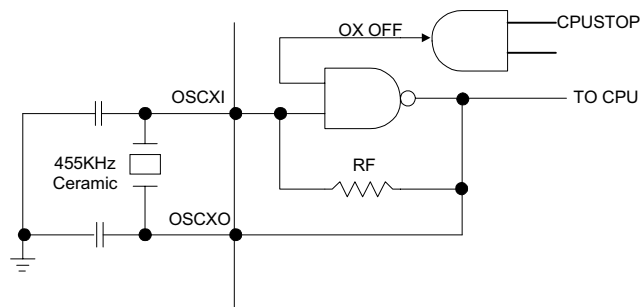


OSC RC oscillator type



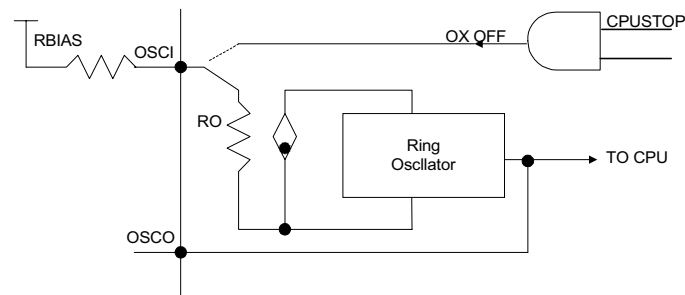
(c) OSCX oscillation

OSCX has two clock oscillators. The software options select the ceramic or RC as the CPU's clock.
OSCX Ceramic oscillator type



OSCX RC oscillator type

If the OSCX is not used, it must be masked to be Ceramic resonator and the OSCXI must be connected to GND.



(d) Control of oscillator

The oscillator control register configuration is shown as blow.

Address	Bit3	Bit2	Bit1	Bit0
\$14	OXS	-	OXM	OXON

OXON: OSCX oscillation on/off.

0: Turn off OSCX oscillation

1: Turn on OSCX oscillation

OXM: switching system clock.

0: select OSC as system clock

1: select OSCX as system clock

OXS: OSCX oscillator type selection

0: OSCX set as ceramic oscillator

1: OSCX set as RC oscillator

(e) Programming notes

It takes at least 5 ms for the OSCX oscillation circuit to go on until the oscillation stabilizes. When switching the CPU system clock from OSC to OSCX, you must wait a minimum of 5ms since the OSCX oscillation goes. However, the start time varies a lot with respect to oscillator characteristics and the condition of use. So the waiting time depends on applications. When switching from OSCX to OSC, and turn off OSCX in one instruction. The OSCX turn off control would be delayed for one instruction cycle automatically to prevent CPU operation error.

5. System clock

The system clock is varies as the clock source changes. The following table shows the instruction execution time according to each frequency of the system clock source.

	32.768 Xtal(OSC)	262K RC(OSC)	455K ceramic Xtal(OSCX)	1.8M RC(OSCX)	2M RC(OSCX)
Cycle time	122.07 μ s	17.778 μ s	8.79 μ s	2.22 μ s	2 μ s

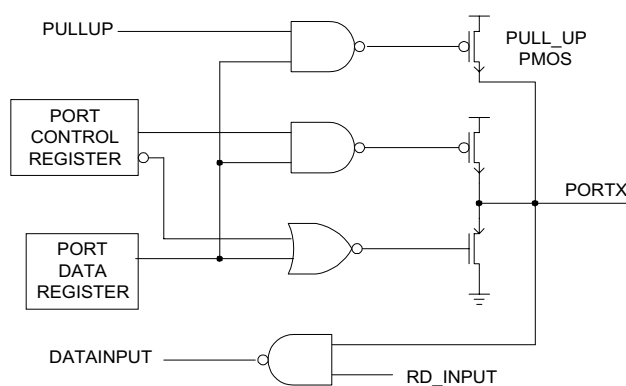
6. I/O PORT

The MCU provides 8-bidirectional I/O pins. Each I/O pin contains pull-up MOS controllable by program. When every I/O is used as input, the PORT control register (PACR, PBCR) controls ON/OFF of the output buffer.

(a)PORTA~B

These ports contain 8-bidirectional I/O ports.

The circuit configuration of PORTA~B as below.



I/O ports of NT66P13 can be accessed by read/write system register. User can output any value to any I/O port bit at any time. Bit3 of the PMOD register controls On/Off of all pull-ups MOS simultaneously. Pull-up MOS also controlled by the port data registers (PA, PB) of each port also. So the pull-up MOS can be turned On/Off.

Memory map addresses are listed as follow:

Address	Bit3	Bit2	Bit1	Bit0
\$08	PORTA.3	PORTA.2	PORTA.1	PORTA.0
\$09	PORTB.3	PORTB.2	PORTB.1	PORTB.0

Port I/O control register:

Address	Bit3	Bit2	Bit1	Bit0
\$0B	PACR.3	PACR.2	PACR.1	PACR.0
\$0C	PBCR.3	PBCR.2	PBCR.1	PBCR.0

I/O control register: PACR.X, PBCR.X (X=0,1,2,3)

1: Use as an output buffer.

0: Use as input buffer (Power on initial).

Port mode register (PMOD)

	Bit3	Bit2	Bit1	Bit0	Function	
\$13	PPULL	PAM2	PAM1	HLM	Bit1,2:Select PA.1,PA.2 as I/O port or PSG output Bit0:Hevey load mode Bit3:Port pull-up control	R/W

PAM1, PAM2: Please sees the PSG

HLM: Enable heavy load mode 0:Disable

1:Enable

PPULL: Port pull-up

0:Disable pull-up

1:Enable pull-up

(b)Port Interrupt

PORTB interrupt (falling edge) is not controlled by Port I/O register. It means that if a interrupt request (IEx is set to 1 & one port bit high go low) is been touched and that the condition is the other port bits are high level whenever the port bit is output or input.

(c)External $\overline{\text{INT}}$

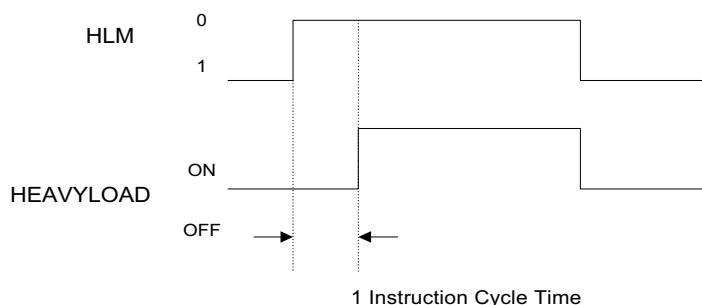
PortA.0 is shared by external interrupts (active low).

7. Heavy load mode (HLM)

The MCU has a heavy load protection circuit for when the battery load becomes heavy. For examples, when an external buzzer sound or an external speaker is turned on. In this mode, the crystal oscillator circuit has been backup for high gain. When setup this mode, more power would be provided to oscillator circuit. Unless it is necessary, be careful not to set this mode with software. Since the mode enter would delay for one instruction. Please activate heavy load driving only after setting HLM at least one instruction wait cycle through the software. Following shows the programming setting.

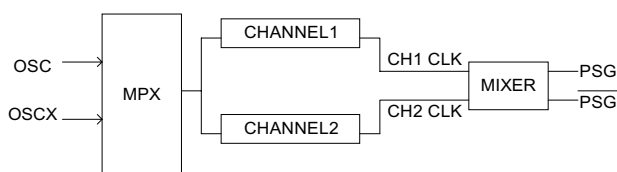
HLM: 0=Heavy load protection mode is released

1=Heavy load protection mode is set.



8. Programmable sound generator (PSG)

PSG has channel1 and channel2. The function block diagram is as follows.



The PSG function provides four subfunctions for wide application.

Programmable sound

Program sound is created by two channels. Every channel can be programmed as follows.

Enable/Disable every channel sounds.

Select every channel sound frequency.

Two channel sounds are mixed into one PSG output.

The PSG output can be controlled at 4 volume levels.

Fine noise

PSG can provide wide-band noise.

The wide-band noise volume can be controlled at 4 volume levels.

Alarm

PSG can provide many alarm functions by software.

The alarm carrier frequency can be programmed individual.

The alarm volume can be controlled at 4 volume levels.

Remote control

The remote control is the only expandable application for PSG sound. Since the remote control frequency is 56.13KHz or 37.92KHz, the software could select the sound frequency.

(a)PSG subblock diagram

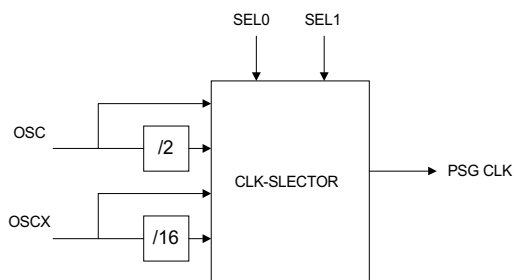
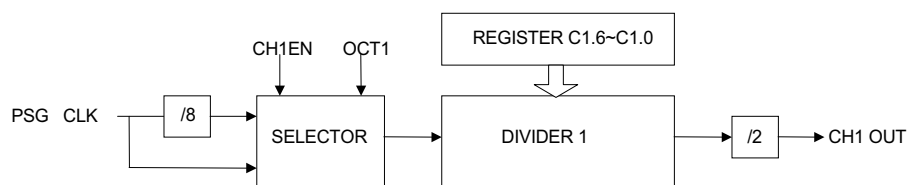


Figure 3 MPX block diagram

SEL1	SEL0	Clk source		PSG clk
0	0	OSC	OSC=32.768K	32.768K
			OSC=262K	262K
0	1	OSC/2	OSC=32.768K	16.384K
			OSC=262K	131K
1	0	OSCX	OSCX=1.8M	1.8M
			OSCX=455K	455K
1	1	OSCX/16	OSCX=1.8M	112.5K
			OSCX=455K	28.4K

The MPX block selects 4 clock sources as PSG clk that provides for the two channel clk sources.

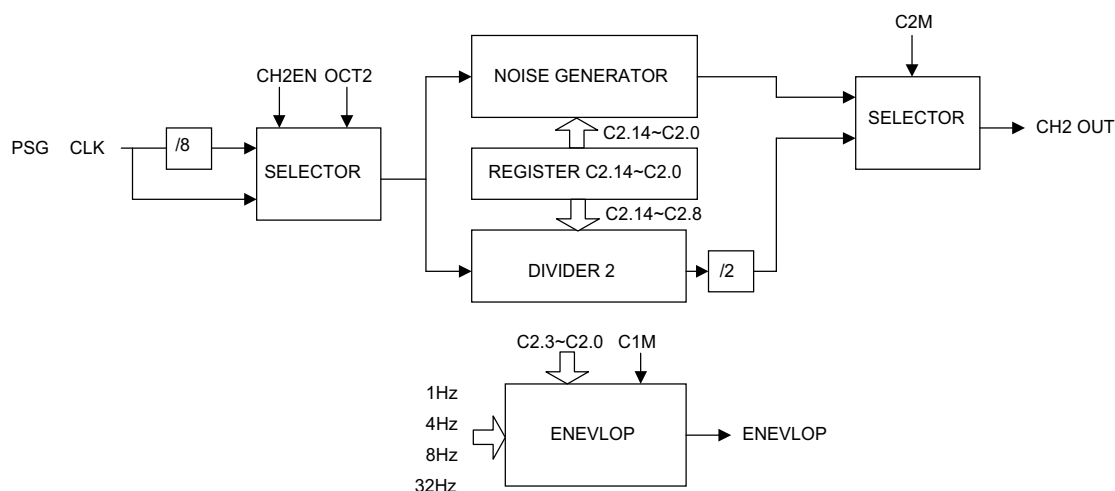
Channel 1



OCT1	Scaling ratio
0	1
1	1/8

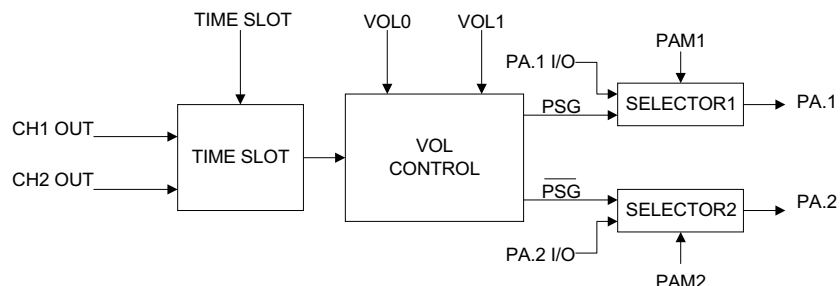
Channel 1 is constructed by a 7-bit pseudo random counter. Channel 1 is enabled/disabled by CH1EN. It creates either a sound frequency or an alarm carrier frequency or a remote carrier frequency.

Channel 2



OCT2	Scaling ratio
0	1
1	1/8

Channel 2 is constructed by a 15-bit pseudo random counter. Channel 2 is enabled/disabled by CH2EN. It can be a 15-bit wide-band noise generator or a 7-bit sound generator. It can also create an alarm envelope signal.

Mixer


C2M	C1M	Function
0	0	CH1 is Sound generator. CH2 is Sound generator.
1	0	CH1 is Sound generator. CH2 is Noise generator.
x	1	CH1 is Sound generator. CH2 is Alarm mode register.

The MIXER mixes CH1-OUT and CH2-OUT into one tone output to PA.1、PA.2, when PAM1=1、PAM2=1. Then the tone output is controlled by the volume control bit into 4 volume levels and in the end outputted by PSG.

PA.1 & PA.2 are controlled by PAM1 & PAM2

PAM2	PAM1	Function
0	0	PA.1: I/O PORT. PA.2:I/O PORT
0	1	PA.1: PSG output. PA.2:I/O PORT
1	0	PA.1: I/O PORT. PA.2:PSG output
1	1	PA.1: PSG output. PA.2:PSG output

SEL1	SEL0	Vol. control
0	0	NO
0	1	YES
1	0	YES
1	1	YES

VOL1	VOL0	Vol. Level
0	0	1
0	1	2
1	0	3
1	1	4

Note: Don't enable two PSG channels together to produce one tone, or it will produce some unpredicted errors. If it is necessary to use 2 channels together (EX. To play two channel melody), don't let the score always be the same tones as we can do, then the unpredicted errors will not occur or it will be ignore through user hearing.

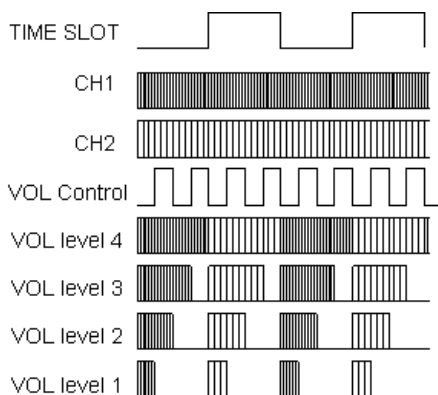
The value N of divider1 is corresponding to the REG C1.6~C1.0 or REG C2.14~C2.8 as shown in the following table:

LSFR (C1.6~C1.0) (C2.14~C2.8)	N	LSFR (C1.6~C1.0) (C2.14~C2.8)	N	LSFR (C1.6~C1.0) (C2.14~C2.8)	N	LSFR (C1.6~C1.0) (C2.14~C2.8)	N
01	127	16	95	12	63	4B	31
02	126	2C	94	24	62	17	30
04	125	59	93	49	61	2E	29
08	124	33	92	13	60	5D	28
10	123	67	91	26	59	3B	27
20	122	4E	90	4D	58	77	26
41	121	1D	89	1B	57	6E	25
03	120	3A	88	36	56	5C	24
06	119	75	87	6D	55	39	23
0C	118	6A	86	5A	54	73	22
18	117	54	85	35	53	66	21
30	116	29	84	6B	52	4C	20
61	115	53	83	56	51	19	19
42	114	27	82	2D	50	32	18
05	113	4F	81	5B	49	65	17
0A	112	1F	80	37	48	4A	16
14	111	3E	79	6F	47	15	15
28	110	7D	78	5E	46	2A	14
51	109	7A	77	3D	45	55	13
23	108	74	76	7B	44	2B	12
47	107	68	75	76	43	57	11
0F	106	50	74	6C	42	2F	10
1E	105	21	73	58	41	5F	9
3C	104	43	72	31	40	3F	8
19	103	07	71	63	39	7F	7
72	102	0E	70	46	38	7E	6
64	101	1C	69	0D	37	7C	5
48	100	38	68	1A	36	78	4
11	99	71	67	34	35	70	3
22	98	62	66	69	34	60	2
45	97	44	65	52	33	40	1
0B	96	09	64	25	32		

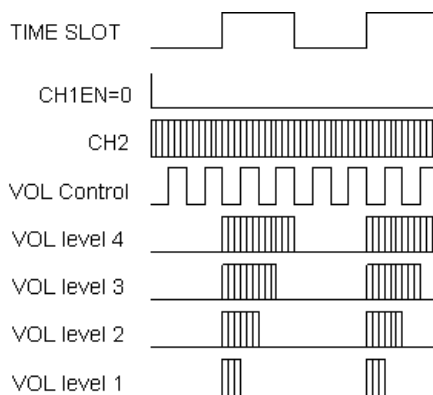
(b)PSG as sound generator

The programmable sound is one of the 4 working modes. The software designer can select up to 16 clock sources as PSG clk. And then select the CH1 and CH2 frequency divided value that is controlled by the value of REG C1.6~C1.0 or C2.14~C2.8. In the end we can select the 4 volume level controlled by VOL0, VOL1. The music tone can output both PSG and $\overline{\text{PSG}}$. We also can control the OCT1, OCT2 bit that shifts the music tone 3 octaves.

Example1: CH1EN=CH2EN=1
 OSCX=1.8M,SEL0=SEL1=1
 So PSG clk =112kHz;Switch clk=28kHz
 Vol. clk=112kHz

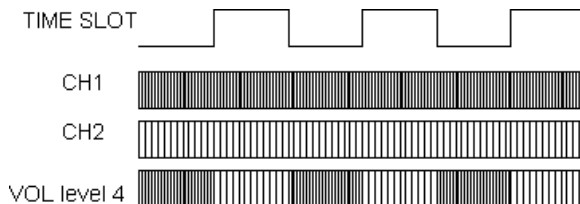


Example2: CH1EN=0;CH2EN=1
 OSCX=1.8M,SEL0=SEL1=1
 So PSG clk =112kHz;Switch clk=28kHz;
 Vol. clk=112kHz



Example3: CH1EN=CH2EN=1
 OSC=32k,SEL0=SEL1=0
 So PSG clk = 32kHz; Switch clk = 32kHz

No vol. control, the VOL level is set to 4 by hardware, so software should set VOL0=VOL1=1.



Note: For 32KHz operations, the volume control cannot be used, because the PWM multiplexing frequency is not high enough to switch sound! If a user want to turn off the PSG completely, the software must disable both channels. User should not turn off the PSG by zero wave from output. Both the CH1EN and CH2EN should be set to "0" for the low power operation mode.

Example 4

If software designer wants to create C2 (channel 1) mixed with F5 (channel 2) sound (the C2, F5 sound frequency please see the Music table1 and Music table2), VOL level=3. He can select the suggestion as follows.

- (1) He first selects CH1EN=CH2EN=1,C1M=C2M=0.
- (2) He can select OSCX=1.8M and SEL0=SEL1=1, so the PSG CLK=112.5KHz.
- (3) Then he can select OCT1=1 and the value of channel 1 LSFR (C1.6~C1.0)=23,so the N =108. Please see the Music table1. So the channel 1 sound frequency=112.5KHz/8/(2×108)=64.10Hz≈the C2 sound frequency.
- (4) Then he can select OCT1=0 and the value of channel 1 LSFR (C1.6~C1.0)=4F,so the N =81. Please see the Music table1. So the channel 1 sound frequency=112.5KHz/1/(2×81)=694.4Hz≈the F5 sound frequency .
- (5) Lastly, he should select the VOL1=1 and VOL0=0, so the VOL level=3.

Note:

The designer provides two crossing tables as an appendix that is what the designer prefers PSG clk=32.768K or PSG clk=112.5K.

PSG as noise generator

The fine noise is created by CH2. If we want to create the single noise, we can make the CH1 music tone output. Otherwise we can mix the wide-band noise and the CH1 music tone into one output through the MIXER. Lastly we can select 4 volume levels controlled by VOL0, VOL1.

(c)PSG as an alarm generator

When PSG is in the alarm mode, the CH1 provides the alarm carrier frequency and the CH2 provides the alarm envelope signal. Lastly we can select 4 volume levels controlled by VOL0, VOL1. The channel 2 low nibble C2.0~C2.3 will be the alarm control register. Channel 1 output would modulate with an ALARM envelope control for 32KHz or 262KHz. The carrier frequency can be programmed by PSG channel 1. In reading this alarm control register, we can read the corresponding output envelope frequency (the 1Hz, 4Hz, 8Hz, 32Hz).

Alarm control register (OSC=32KHz or 262KHz)

\$19	C2.3	C2.2	C2.1	C2.0	Alarm output control
	0	0	0	0	DC envelop
	X	X	X	1	1Hz output
	X	X	1	X	4Hz output
	X	1	X	X	8Hz output
	1	X	X	X	32Hz output

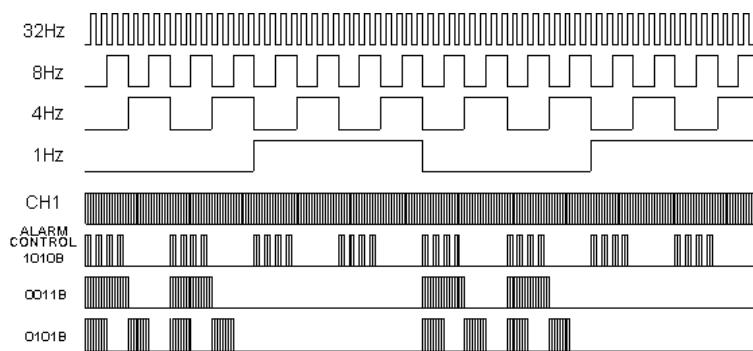


Figure 4 Alarm modulation output for OSC=32.768KHz or OSC=262KHz.

(d)PSG as remote control

The remote control is only an expandable application for PSG sound. We can select the CH1 as tone output and the CH2 will create alarm frequency envelope signal.

When PSG channel is programmed in the ALARM mode. Programmer can set ALARM mode register to "0000B". Program the adequate frequency output to PSG output. Then use PAM1 or PAM2 control the envelope of code. In this way, remote control function can be implemented easily.

The remote frequency =56.73KHz or 37.92KHz.

The software should select OSCX=455KHz, SEL=1 and SEL0=0, so that the PSG CLK=455KHz.

Then select channel 1 alarm mode (C1M=1), and OCT1=0, C2.0~C2.3 are set to 00H. VOL1, VOL2=1,1.

Then select C1.6~C1.0=7E, so that N=6 and the PSG output frequency=455KHz/1/(2×6)=37.92KHz.

Or select C1.6~C1.0=78, so that N=4 and the PSG output frequency=455KHz/1/(2×4)=56.87KHz.

9. Timer

NT66P13 has one 8-bit timer. The timer consists of an 8-bit up counter and an 8-bit preload register.

The timers provide the following functions:

- 8-bit up-counting timer/counter.
- Automatic re-loads counter.
- 8-bit prescaler.
- Interrupt on overflow from \$FF to \$00.

(a) Configuration and Operation

Timer-0 consists of an 8-bit write-only timer load register (TL0L, TL0H), and an 8-bit read-only timer counter (TC0L, TC0H). The counter and load register both have low order digit and high order digit. Writing data into the timer load register (TL0L, TL0H) can initialize the timer counter.

Load register programming: The low-order digit should be written first, and then the high-order digit. The timer counter is automatically loaded with the contents of the load register when the high order digit is written or counter counts overflow from \$FF to \$00.

Timer Load Register: Since register H would control the physical READ and WRITE operations.

Please follow these rules:

Write Operation:

Low nibble first

High nibble to update the counter

Read Operation:

High nibble first;

Low nibble followed.

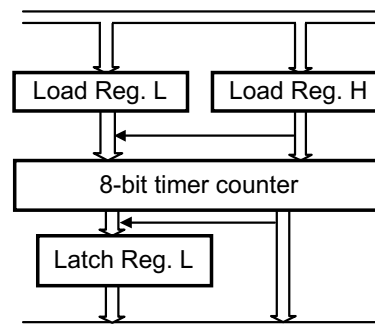


Figure 5 Timer Load register Configure

(b) Timer0 Interrupt

The timer overflow will generate an internal interrupt request, when the counter counts overflow from \$FF to \$00. If the interrupt enable flag is enabled, then a timer interrupt service routine will start. This can also be used to wake CPU from HALT mode.

(c) Timer0 mode register (TM0)

The 8-bit counter prescaler overflow output pulses. TM0 are 4-bit registers used for timer control as shown in Table1. The register selects the input clock sources in the timer.

Table1: Timer0 Mode registers (\$02)

TM0.3	TM0.2	TM0.1	TM0.0	Prescaler	Clock Source
0	0	0	0	/2048	System clock
0	0	0	1	/512	System clock
0	0	1	0	/128	System clock
0	0	1	1	/32	System clock
0	1	0	0	/8	System clock
0	1	0	1	/4	System clock
0	1	1	0	/2	System clock
0	1	1	1	External	INT0

TM0.3 control function:

0: without Auto-Reload function

1: Auto-Reload function

10. Base Timer

The MCU has a base timer that is shared with the warm-up timer and the clock source is OSC (Low frequency oscillation: Crystal 32.768KHz or RC 262KHz). After MCU is reset, it counts at every clock-input signal. When it counts to \$FF, right after next clock input, counter counts to \$00 and generates an overflow. This causes the interrupt of base timer interrupt request flag to 1. Therefore, base timer can function as an interval timer periodically, generating overflow output as every 256th clock signal output.

The timer accepts 4096Hz or 32KHz clock, and base timer generates an accurate timing interrupt. This base time prescaler can be reset by a program for accurate timing.

This clock-input source is selected by BTM register.

Address	Bit3	Bit2	Bit1	Bit0	Function
\$03	BTM.3	BTM.2	BTM.1	BTM.0	Base timer mode register

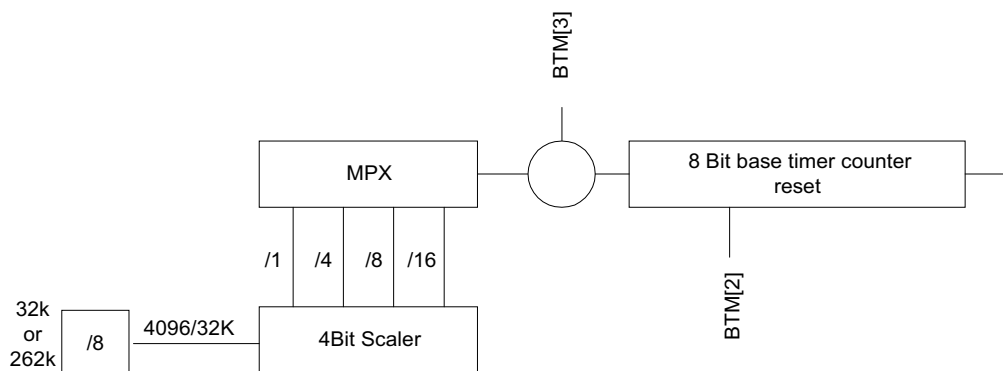
BTM.3=0: Disable the base timer

BTM.3=1: Enable the base timer

BTM.2=0: Non reset the base timer

BTM.2=1: reset the base timer

BTM.1	BTM.0	Prescaler Ratio	Clock source
0	0	/1	4096Hz or 32KHz
0	1	/4	4096Hz or 32KHz
1	0	/8	4096Hz or 32KHz
1	1	/16	4096Hz or 32KHz



11. LCD Driver

The LCD driver contains a controller, a voltage generator, 4 common signal pins and 34 segment driver pins. There is 1/4 duty and 1/3 bias driving mode programmable. **System register \$15 should be set '1'.**

The LCD SEG1~30 can also be used as output port, it is selected by the bit 2 of the system register \$16. When SEG1~30 is to be output port, you write data to bit 0 of the same addresses (350H-36DH). LCD RAM could be used as data memory if you need. When the "STOP" instruction is executed, the LCD will be turned off, but the data of LCD RAM keeps the same value before executing the "STOP" instruction.

(a) LCD Control Register

Add.	Bit 3	Bit 2	Bit 1	Bit 0
\$15	LPS1	LPS0	LCDOFF	Should be set "1"

LCDOFF: LCD on/off switch.
0: LCD on. 1: LCD off.

LPS1, LPS0: LCD clock frequency control
0,0: LCDCLK = OSC/64
0,1: LCDCLK = OSC/512
1,0: LCDCLK = System clock/512
1,1: LCDCLK = System clock/4096

*System clock= Instruction cycle time

Frame frequency=LCDCLK/16

CLK Frequency	LPS1, LPS0			
	0,0	0,1	1,0	1,1
OSC=32kHz (#), OSCX=455kHz	32Hz	4Hz	1Hz	1/8Hz
OSC=32kHz, OSCX=455kHz (#)	32Hz	4Hz	14Hz	1.7Hz
OSC=32kHz (#), OSCX=1.8MHz	32Hz	4Hz	1Hz	1/8Hz
OSC=32kHz, OSCX=1.8MHz (#)	32Hz	4Hz	55Hz	6.9Hz
OSC=32kHz(#), OSCX=2MHz	32Hz	4Hz	1Hz	1/8Hz
OSC=32kHz, OSCX=2MHz (#)	32Hz	4Hz	61Hz	7.6Hz
OSC=262kHz (#), OSCX=455kHz	256Hz	32Hz	8Hz	1Hz
OSC=262kHz, OSCX=455kHz (#)	256Hz	32Hz	14Hz	1.7Hz
OSC=262kHz (#), OSCX=1.8MHz	256Hz	32Hz	8Hz	1Hz
OSC=262kHz, OSCX=1.8MHz (#)	256Hz	32Hz	55Hz	6.9Hz
OSC=262kHz (#), OSCX=2MHz	256Hz	32Hz	8Hz	1Hz
OSC=262kHz, OSCX=2MHz (#)	256Hz	32Hz	61Hz	7.6Hz

The clk before (#) is selected as CPU system clk.

Frame frequency=LCDCLK/16 (32Hz)

When LCD is set SCAN OUT, COMx are pulled high. It is easy to implement the keyboard scan.

When CPU is in STOP mode, the COMx and SEGx are pulled low. It can easily be waken up by keyboard scan (Port interrupt).

When CPU is in HALT mode, the COMx and SEGx are normal. It can easily be waken up by base timer, timer0 or port interrupt.

[illegible]

Build-in special LCD power control for LCD power modulation.

0: LCD segment output 1: output ports.

(c) Configuration of LCD RAM

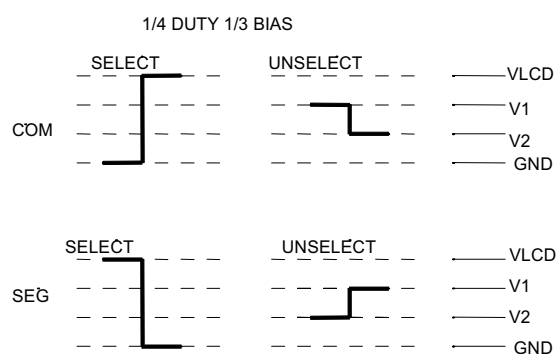
LCD 1/4 duty, 1/3 bias (COM1~4,SEG1~34)

Ver 1.0

SEG1-30 is used as scan output port.

Address	Bit0	Address	Bit0	Address	Bit0	Address	Bit0
350H	SEG1	358H	SEG9	360H	SEG17	368H	SEG25
351H	SEG2	359H	SEG10	361H	SEG18	369H	SEG26
352H	SEG3	35AH	SEG11	362H	SEG19	36AH	SEG27
353H	SEG4	35BH	SEG12	363H	SEG20	36BH	SEG28
354H	SEG5	35CH	SEG13	364H	SEG21	36CH	SEG29
355H	SEG6	35DH	SEG14	365H	SEG22	36DH	SEG30
356H	SEG7	35EH	SEG15	366H	SEG23		
357H	SEG8	35FH	SEG16	367H	SEG24		

(d)LCD waveform



12. Interrupt

4 interrupt sources are available on NT66P13:

- External interrupt ($\overline{INT0}$)
- Timer0 interrupt
- Base timer interrupt
- Port's falling edge detection interrupt($\overline{INT1}$)

The configuration of system register \$0:

	Bit 3	Bit 2	Bit 1	Bit 0	Function
\$00	IEX	IET0	IEBT	IEP	1:Enable / 0:Disable
\$01	IRQX	IRQT0	IRQBT	IRQP	1:Request / 0:No request

(a)External Interrupt ($\overline{INT0}$)

External interrupt is shared with the PA.0, falling edge active. When the bit 3 of the register \$0 (IEX) is set to 1, the external interrupt is enabled, writing a "0" to PA.0 will generate an external interrupt.

(b)Timer 0 interrupt, Base timer interrupt, Port interrupt ($\overline{INT1}$)

If IEx=1 then all valid interrupt requests will cause interrupt. The overflow of timer 0 will create the interrupt of timer 0. The overflow of the Base timer will create the interrupt of the Base timer. The falling edge of every port in PORTB will create $\overline{INT1}$ interrupt (The condition is that the other port must be input/output high level).

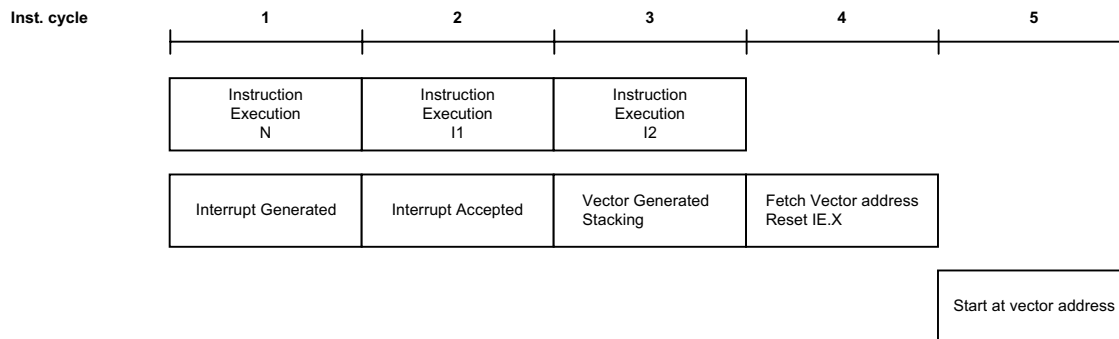
The Enable flags and Request flags

Both the Enable flags and Request flags can be read or written by the software.

But the Request flags will be set "1" by the hardware interrupt, the Enable flags will be reset by the hardware when the interrupt service routine is entered.

(c)Interrupt Servicing Sequence Diagram:

In NT6610C CPU interrupt services routine, the user can enable any interrupt enable flag before returning from interrupt. The frequently asked question is when the next interrupt would be serviced? Will the nesting interrupt happen? From the servicing sequence timing diagram, if interrupt request is ready and instruction execution N is IE enable. Then the interrupt can start right after the next two instructions: I1 or instruction I2 disable the interrupt request or enable flag, then interrupt service sequence would be terminated.

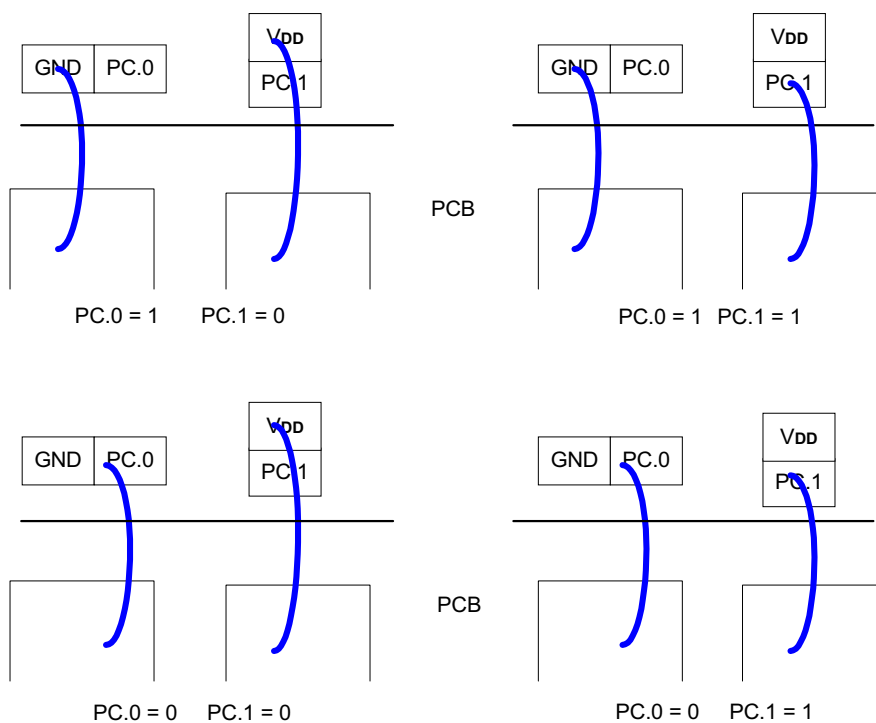


13. Options

(a) Bonding options

System register \$0A is reserved for the user .It is opened for system developer to select these 2 bonding options, selecting subprogram that is programmed by the user.

\$0A.1 (PC.1)	\$0A.0 (PC.0)	
0	0	goto subroutine 1
0	1	goto subroutine 2 (Default)
1	0	goto subroutine 3
1	1	goto subroutine 4



NT66P14 Bonding Option

(b) Code option

Oscillator (OSC) type:

0= Set as 32.768KHz crystal (Default)

1= Set as 262KHz RC

14. HALT and STOP mode

After the execution of HALT instruction, NT66P13 will enter halt mode.

In halt mode, CPU will stop operating. But peripheral circuit (Timer & Base timer) will keep operating.

After the execution of STOP instruction, NT66P13 will enter stop mode.

In stop mode, the whole chip (including oscillator) will stop operating.

In HALT mode, NT66P13 can be waked up if any interrupt occurs.

In STOP mode, NT66P13 can be waked up if port interrupt occurs.

15. Warm-up counter

In RC mode, the warm-up counter prescaler is divided by 27 (128).

In Crystal mode, the warm-up counter prescaler is divided by 215 (65536).

Instruction set

All instructions are one cycle and one word instruction. The characteristic is memory-oriented operation.

Arithmetic and Logical Instruction

Accumulator Type

Mnemonic	Instruction Code	Function	Flag Change
ADC X(B)	00000 0bbb xxx xxxx	$AC \leftarrow Mx + AC + CY$	CY
ADCM X(B)	00000 1bbb xxx xxxx	$AC, Mx \leftarrow Mx + AC + CY$	CY
ADD X(B)	00001 0bbb xxx xxxx	$AC \leftarrow Mx + AC$	CY
ADDM X(B)	00001 1bbb xxx xxxx	$AC, Mx \leftarrow Mx + AC$	CY
SBC X(B)	00010 0bbb xxx xxxx	$AC \leftarrow Mx + -AC + CY$	CY
SBCM X(B)	00010 1bbb xxx xxxx	$AC, Mx \leftarrow Mx + -AC + CY$	CY
SUB X(B)	00011 0bbb xxx xxxx	$AC \leftarrow Mx + -AC + 1$	CY
SUBM X(B)	00011 1bbb xxx xxxx	$AC, Mx \leftarrow Mx + -AC + 1$	CY
EOR X(B)	00100 0bbb xxx xxxx	$AC \leftarrow Mx \oplus AC$	
EORM X(B)	00100 1bbb xxx xxxx	$AC, Mx \leftarrow Mx \oplus AC$	
OR X(B)	00101 0bbb xxx xxxx	$AC \leftarrow Mx AC$	
ORM X(B)	00101 1bbb xxx xxxx	$AC, Mx \leftarrow Mx AC$	
AND X(B)	00110 0bbb xxx xxxx	$AC \leftarrow Mx \& AC$	
ANDM X(B)	00110 1bbb xxx xxxx	$AC, Mx \leftarrow Mx \& AC$	
SHR	11110 0000 000 0000	$0 \rightarrow AC[3]; AC[0] \rightarrow CY;$ AC shift right one bit	CY

Immediate Type

Mnemonic	Instruction Code	Function	Flag Change
ADI X,I	01000 iiiii xxx xxxx	$AC \leftarrow Mx + I$	CY
ADIM X,I	01001 iiiii xxx xxxx	$AC, Mx \leftarrow Mx + I$	CY
SBI X,I	01010 iiiii xxx xxxx	$AC \leftarrow Mx + -I + 1$	CY
SBIM X,I	01011 iiiii xxx xxxx	$AC, Mx \leftarrow Mx + -I + 1$	CY
EORIM X,I	01100 iiiii xxx xxxx	$AC, Mx \leftarrow Mx \oplus I$	
ORIM X,I	01101 iiiii xxx xxxx	$AC, Mx \leftarrow Mx \vee I$	
ANDIM X,I	01110 iiiii xxx xxxx	$AC, Mx \leftarrow Mx \wedge I$	

* In the assembler ASM66 V1.0, EORIM mnemonic is EORI. However, EORI has the same operation identical with EORIM. It is true for the ORIM with respect to ORI, and ANDIM with respect to ANDI.

Decimal Adjust

Mnemonic	Instruction Code	Function	Flag Change
DAA X	11001 0110 xxx xxxx	$AC, Mx \leftarrow$ Decimal adjust for add.	CY
DAS X	11001 1010 xxx xxxx	$AC, Mx \leftarrow$ Decimal adjust for sub.	CY

Transfer Instruction

Mnemonic	Instruction Code	Function	Flag Change
LDA X(B)	00111 0bbb xxx xxxx	AC $\leftarrow$ Mx	
STA X(B)	00111 1bbb xxx xxxx	Mx $\leftarrow$ AC	
LDI X,I	01111 iiii xxx xxxx	AC,Mx $\leftarrow$ I	

Control Instruction

Mnemonic	Instruction Code	Function	Flag Change
BAZ X	10010 xxxx xxx xxxx	PC $\leftarrow$ X if AC=0	
BNZ X	10000 xxxx xxx xxxx	PC $\leftarrow$ X if AC $\neq$ 0	
BC X	10011 xxxx xxx xxxx	PC $\leftarrow$ X if CY=1	
BNC X	10001 xxxx xxx xxxx	PC $\leftarrow$ X if CY $\neq$ 1	
BA0 X	10100 xxxx xxx xxxx	PC $\leftarrow$ X if AC(0)=1	
BA1 X	10101 xxxx xxx xxxx	PC $\leftarrow$ X if AC(1)=1	
BA2 X	10110 xxxx xxx xxxx	PC $\leftarrow$ X if AC(2)=1	
BA3 X	10111 xxxx xxx xxxx	PC $\leftarrow$ X if AC(3)=1	
CALL X	11000 xxxx xxx xxxx	ST $\leftarrow$ CY; PC +1 PC $\leftarrow$ X(Not include p)	
RTNW H;L	11010 000h hhh llll	PC $\leftarrow$ ST; TBR $\leftarrow$ hhhh; AC $\leftarrow$ llll	
RTNI	11010 1000 000 0000	CY;PC $\leftarrow$ ST	CY
HALT	11011 0000 000 0000		
STOP	11011 1000 000 0000		
JMP X	1110p xxxx xxx xxxx	PC $\leftarrow$ X(Include p)	
TJMP	11110 1111 111 1111	PC $\leftarrow$ (PC11-PC8) (TBR) (AC)	
NOP	11111 1111 111 1111	No Operation	

Where

PC	Program counter	I	Immediate data
AC	Accumulator	$\oplus$	Logical exclusive OR
-AC	Complement of accumulator		Logical OR
CY	Carry flag	&	Logical AND
Mx	Data memory	bbb	RAM bank
P	ROM page		
ST	Stack	TBR	Table Branch Register

Absolute Maximum Rating*

DC Supply Voltage -0.3V to +7.0V

Input Voltage -0.3V to VDD+0.3V

Operating Ambient Temperature -10°C to +60°C

Storage Temperature -55°C to +125°C

***Comments**

Stresses above those listed under "**Absolute Maximum Ratings**" may cause permanent damage to this device. These are stress ratings only. Functional operation of this device at these or any other conditions above those indicated in the operational sections of this specification is not implied or intended. Exposure to the absolute maximum rating conditions for extended periods may affect device reliability.

DC Electrical Characteristics

(VDD=3.0V, GND=0V, TA=25°C, Fosc=32.768KHz, FoscX is not used, unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Operating Voltage	VDD	2.5	3	6.0	V	
Operating Current	IOP	-	10	20	μA	All output pins unload execute NOP instruction exclude LCD bias current, LPD off
LCD voltage divider resistor	RLCD	-	275	-	KΩ	
Standby Current	ISB1	-	2	4	μA	All output pins unload (HALT mode) exclude LCD bias current, LPD off
Standby Current	ISB2	-	-	1	μA	All output pins unload (STOP mode), LCD off, LPD off
Input High Voltage	VIH	0.7×VDD 0.85×VDD	-	VDD+0.3 VDD+0.3	V	PORTA, PORTB INT0, RESET
Input Low Voltage	VIL	-0.3	-	0.3×VDD 0.15×VDD	V	PORTA, PORTB INT0, RESET
Drive-high resistance	ROH	-	300	-	KΩ	PORTA, PORTB (IOH = -10μA, VOH = 0).
Output high voltage	VOH1	0.7×VDD	-	-	V	PORTA.0, PORTA.3, PORTB (IOH = -2mA).
Output low voltage	VOL1	-	-	0.8	V	PORTA.0, PORTA.3, PORTB (IOL = 2mA).
Output high voltage	VOH2	0.7×VDD	-	-	V	PORTA.1, PORTA.2 or PSG output, IOH = -5mA.
Output low voltage	VOL2	-	-	0.8	V	PORTA.1, PORTA.2 or PSG output, IOL = 5mA.
Output high voltage	VOH3	2.8	-	-	V	SEGx, C=50P, rise time<1000ns
Output low voltage	VOL3	-	-	0.2	V	SEGx
Output high voltage	VOH4	VDD-0.6	-	-	V	SEG1 - 30to be output port, IOH = -1mA
Output low voltage	VOL4	-	-	0.8	V	SEG1 - 30to be output port, IOL = 1mA
Output high voltage	VOH5	VDD-1.0	-	-	V	COMx, IOH = -1mA.
Output low voltage	VOL5	-	-	0.8	V	COMx, IOL = 1mA.
LCD lighting	ILCD	-	8	10	μA	VDD=3V, exclude CPU core operation current

Operation frequency vs. ISB1

ISB1X = (Frequency/32.768KHz)×ISB1×0.8, (VDD = 3.0V).

Operation frequency vs. IOP

IOPX = (Frequency/32.768KHz)×IOP×0.8, (VDD = 3.0V).

HLM vs. IOP, ISB1 and ISB2

If HLM = 1, IOPX = IOP×2, ISB2X = ISB2×2.

LPD Circuitry (GND = 0V, TA = 25°C, Fosc = 32.768KHz, unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
LPD-detected Voltage	VLPD	-	2.0	-	V	

AC Characteristics ($V_{DD}=3.0V$, $GND=0V$, $T_A=25^{\circ}C$, $F_{osc}=32.768KHz$, unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Oscillation Start Time	t_{STT}	-	2	5	s	
Frequency Stability	$ \Delta F /F$	-	-	1	PPM	$[F(3.0)-F(2.5)]/F(3.0)$, crystal oscillator

AC Characteristics ($V_{DD}=3.0V$, $GND=0V$, $T_A=25^{\circ}C$, $F_{osc}=262KHz$, FOSC_X stop, unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Oscillation Start Time	t_{STT}	-	-	100	μs	
Frequency Stability	$ \Delta F /F$	-	-	10	%	$[F(3.0)-F(2.5)]/F(3.0)$, Bias resistance accuracy within 1%

AC Characteristics ($V_{DD}=3.0V$, $GND=0V$, $T_A=25^{\circ}C$, $F_{osc}=262KHz$, FOSC_X stop, unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Frequency Stability	$ \Delta F /F$	-	-	10	%	$[F(4.5)-F(3.6)]/F(4.5)$, Bias resistance accuracy within 1%

Typical RC oscillator Resistor vs. Frequency: (for reference only)

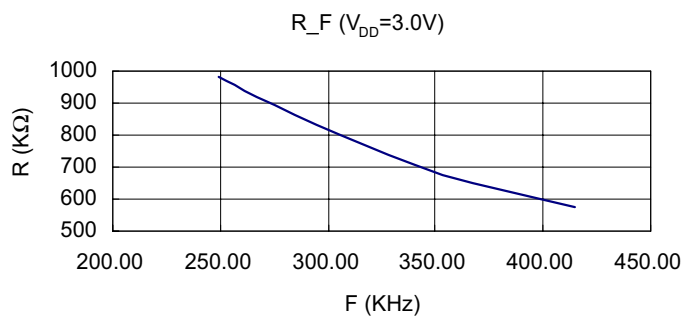


Figure 7 Resistor vs. FOSC

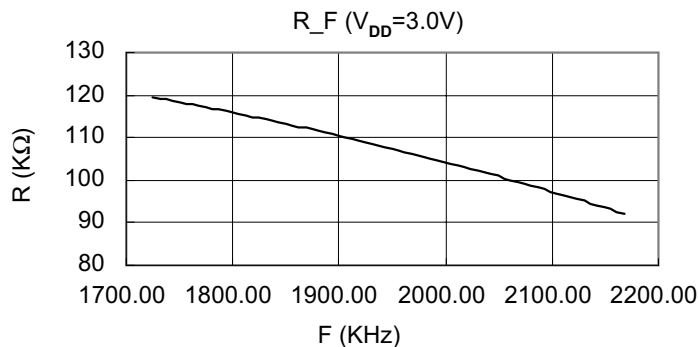


Figure 8 Resistor vs. FOSC_X

Application Circuit (for reference only)
AP1:

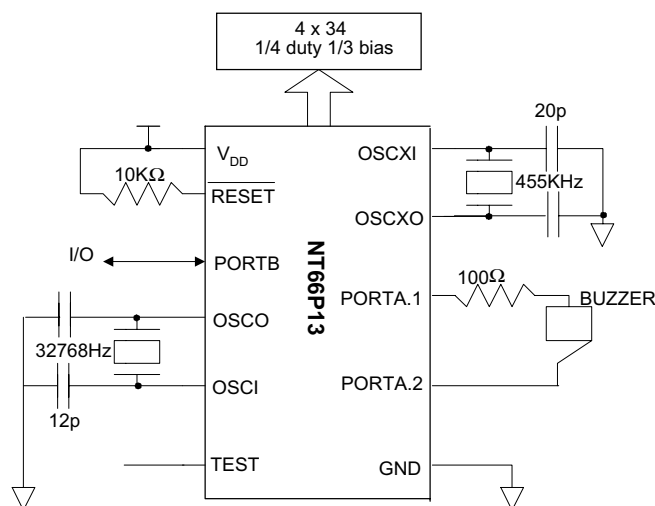
OSC: Crystal oscillator 32.768KHz(code option)

OSCX: Ceramic oscillator 455KHz

PORTB: I/O

PORTA.1, PORTA.2: ALARM output

LCD: Internal LCD 1/4duty, 1/3bias

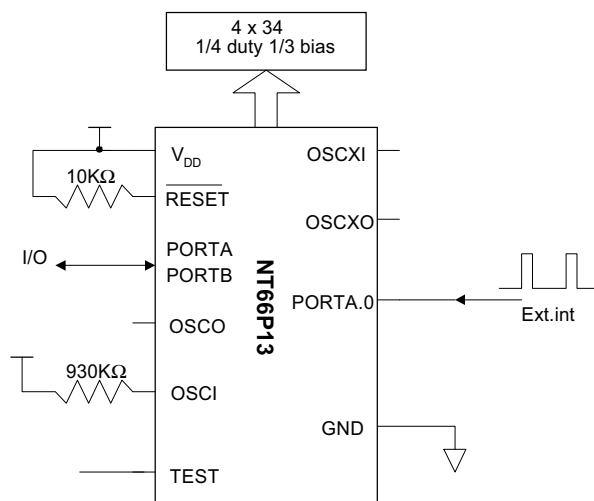

AP2:

OSC: RC oscillator 262KHz(mask option)

LCD: Internal LCD 1/4 duty, 1/3 bias

PORTA, PORTB: I/O

PORTA.0: External interrupt



AP3:

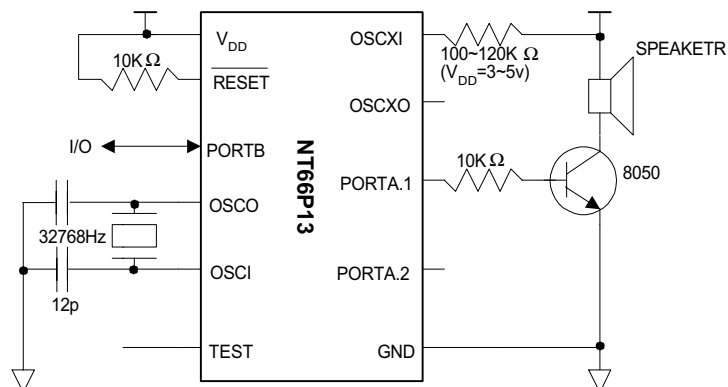
OSC: Crystal oscillator 32.768KHz(mask option)

OSCX: RC oscillator 1.8MHz

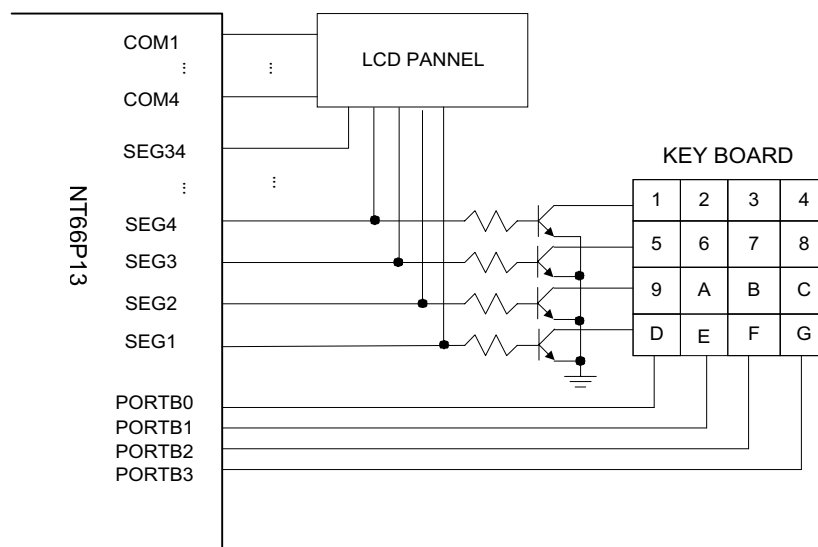
PORTB: I/O

PORTA.1: PSG output

PORTA.2: $\overline{\text{PSG}}$ output


AP4:

Internal LCD bias.1/4DUTY 1/3bias

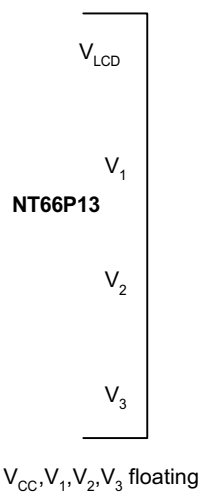


SEG1~SEG4 as SCAN output port

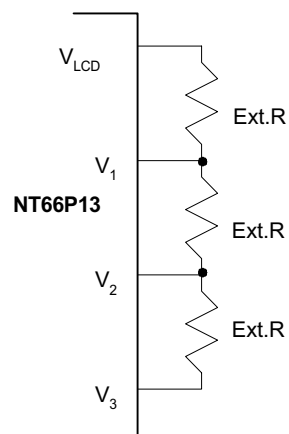
AP5:

Large LCD panel: External LCD bias

1/3 Bias
Normal LCD pannel



1/3 Bias
Large LCD pannel



Music Table1

Following is the music scale reference table for channel 1(or channel 2) under OSCX=1.8MHz. Up to 6 octave is possible.
Music scale data for 1.8M OSCX and SEL0=SEL1=1

Note	Ideal freq.	N	OCT1 /OCT2	LSFR (C1.6~C1.0) (C2.14~C2.8)	Real freq.	Error%	Note	Ideal freq.	N	OCT1 /OCT2	LSFR (C1.6~C1.0) (C2.14~C2.8)	Real freq.	Error%
B1	61.74	114	1	42	61.75	0.03%	B4	493.88	114	0	42	494.04	0.03%
C2	65.41	108	1	23	65.19	-0.34%	C5	523.25	108	0	23	521.48	-0.34%
D2	73.42	96	1	0B	73.33	-0.11%	D5	587.33	96	0	0B	586.67	-0.11%
E2	82.41	85	1	54	82.82	0.51%	E5	659.26	85	0	54	662.59	0.51%
F2	87.31	81	1	4F	86.91	-0.45%	F5	698.46	81	0	4F	695.31	-0.45%
G2	98.00	72	1	43	97.78	-0.23%	G5	783.99	72	0	43	782.22	-0.23%
A2	110.00	64	1	09	110.00	0.00%	A5	880.00	64	0	09	880.00	0.00%
B2	123.47	57	1	1B	123.51	0.03%	B5	987.77	57	0	1B	988.07	0.03%
C3	130.81	54	1	5A	130.37	-0.34%	C6	1046.50	54	0	5A	1042.96	-0.34%
D3	146.83	48	1	37	146.67	-0.11%	D6	1174.66	48	0	37	1173.33	-0.11%
E3	164.81	43	1	76	163.72	-0.66%	E6	1318.51	43	0	76	1309.77	-0.66%
F3	174.61	40	1	31	176.00	0.79%	F6	1396.91	40	0	31	1408.00	0.79%
G3	196.00	36	1	1A	195.56	-0.23%	G6	1567.98	36	0	1A	1564.44	-0.23%
A3	220.00	32	1	25	220.00	0.00%	A6	1760.00	32	0	25	1760.00	0.00%
B3	246.94	29	1	2E	242.76	-1.69%	B6	1975.53	29	0	2E	1942.07	-1.69%
C4	261.63	27	1	3B	260.74	-0.34%	C7	2093.00	27	0	3B	2085.93	-0.34%
D4	293.66	24	1	5C	293.33	-0.11%	D7	2349.32	24	0	5C	2346.67	-0.11%
E4	329.63	21	1	66	335.24	1.70%	E7	2637.02	21	0	66	2681.90	1.70%
F4	349.23	20	1	4C	352.00	0.79%	F7	2793.83	20	0	4C	2816.00	0.79%
G4	392.00	18	1	32	391.11	-0.23%	G7	3135.96	18	0	32	3128.89	-0.23%
A4	440.00	16	1	4A	440.00	0.00%	A7	3520.00	16	0	4A	3520.00	0.00%
B4	493.88	14	1	2A	502.86	1.82%	B7	3951.07	14	0	2A	4022.86	1.82%

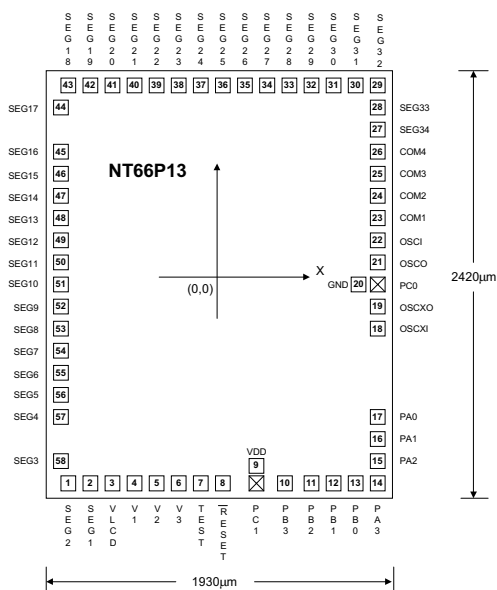
Music Table2

Following is the music scale reference table for channel 1(or channel 2) under OSC=32.768KHz. Up to 4-octave is possible.
Music scale data for 32K OSC and SEL0=SEL1=0

Note	Ideal freq.	N	OCT1 /OCT2	LSFR (C1.6~C1.0) (C2.14~C2.8)	Real freq.	Error%	Note	Ideal freq.	N	OCT1 /OCT2	LSFR (C1.6~C1.0) (C2.14~C2.8)	Real freq.	Error%
A1	55.00	37	1	0D	55.35	0.64%	C4	261.63	63	0	12	260.06	-0.60%
B1	61.74	33	1	52	62.06	0.53%	D4	293.66	56	0	36	292.57	-0.37%
C2	65.41	31	1	4B	66.06	1.01%	E4	329.63	50	0	2D	327.68	-0.59%
D2	73.42	28	1	5D	73.14	-0.37%	F4	349.23	47	0	6F	348.60	-0.18%
E2	82.41	25	1	6E	81.92	-0.59%	G4	392.00	42	0	6C	390.10	-0.48%
F2	87.31	23	1	39	89.04	1.99%	A4	440.00	37	0	0D	442.81	0.64%
G2	98.00	21	1	66	97.52	-0.48%	B4	493.88	33	0	52	496.48	0.53%
A2	110.00	19	1	19	107.79	-2.01%	C5	523.25	31	0	4B	528.52	1.01%
B2	123.47	17	1	65	120.47	-2.43%	D5	587.33	28	0	5D	585.14	-0.37%
C3	130.81	125	0	04	131.07	0.20%	E5	659.26	25	0	6E	655.36	-0.59%
D3	146.83	112	0	0A	146.29	-0.37%	F5	698.46	23	0	39	712.35	1.99%
E3	164.81	99	0	11	165.49	0.41%	G5	783.99	21	0	66	780.19	-0.48%
F3	174.61	94	0	2C	174.30	-0.18%	A5	880.00	19	0	19	862.32	-2.01%
G3	196.00	84	0	29	195.05	-0.48%	B5	987.77	17	0	65	963.76	-2.43%
A3	220.00	74	0	50	221.41	0.64%	C6	1046.50	16	0	4A	1024.00	-2.15%
B3	246.94	66	0	62	248.24	0.53%	D6	1174.66	14	0	2A	1170.29	-0.37%

Ordering Information

Part No.	Package
NT66P13H	CHIP FORM
NT66P13F	QFP 100

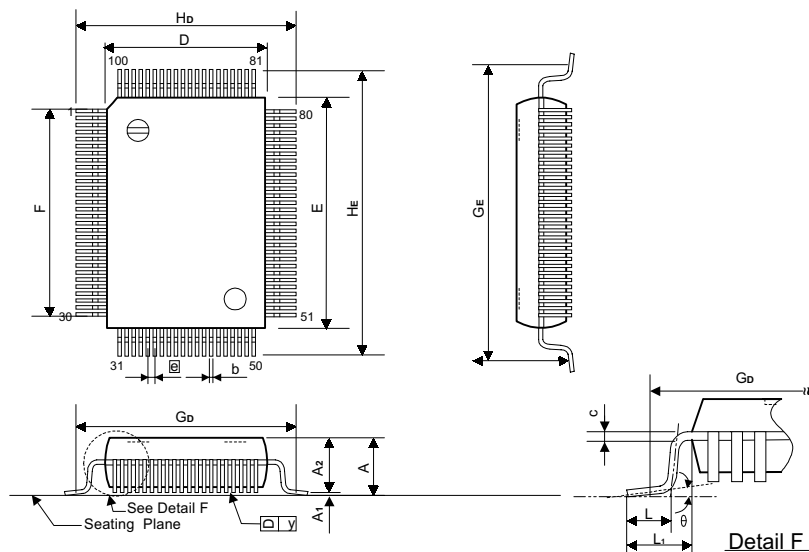
Bonding diagram


Substrate connect to GND

Pad No.	Designation	X(μm)	Y(μm)	Pad No.	Designation	X(μm)	Y(μm)
1	SEG2	-890.55	-1121.05	29	SEG[32]	884.45	1135.00
2	SEG1	-720.55	-1135.00	30	SEG[31]	759.45	1135.00
3	VLCD	-595.55	-1135.00	31	SEG[30]	634.45	1135.00
4	V1	-470.55	-1135.00	32	SEG[29]	509.45	1135.00
5	V2	-345.55	-1135.00	33	SEG[28]	384.45	1135.00
6	V3	-220.55	-1135.00	34	SEG[27]	259.45	1135.00
7	TEST	-90.55	-1135.00	35	SEG[26]	134.45	1135.00
8	RESET	39.45	-1135.00	36	SEG[25]	9.45	1135.00
9	VDD	204.45	-1030.00	37	SEG[24]	-115.55	1135.00
bonding option	PC1	204.45	-1135.00	38	SEG[23]	-240.55	1135.00
10	PB3	364.45	-1135.00	39	SEG[22]	-365.55	1135.00
11	PB2	489.45	-1135.00	40	SEG[21]	-490.55	1135.00
12	PB1	614.45	-1135.00	41	SEG[20]	-615.55	1135.00
13	PB0	739.45	-1135.00	42	SEG[19]	-740.55	1135.00
14	PA3	884.45	-1135.00	43	SEG[18]	-865.55	1135.00
15	PA2	884.45	-1010.00	44	SEG[17]	-890.55	990.00
16	PA1	884.45	-885.00	45	SEG[16]	-890.55	740.00
17	PA0	884.45	-760.00	46	SEG[15]	-890.55	615.00
18	OSCXI	884.45	-260.00	47	SEG[14]	-890.55	490.00
19	OSCXO	884.45	-135.00	48	SEG[13]	-890.55	365.00
20	GND	784.45	-10.00	49	SEG[12]	-890.55	240.00
bonding option	PC0	884.45	-10.00	50	SEG[11]	-890.55	115.00
21	OSCO	884.45	115.00	51	SEG[10]	-890.55	-10.00
22	OSCI	884.45	240.00	52	SEG[9]	-890.55	-135.00
23	COM1	884.45	365.00	53	SEG[8]	-890.55	-260.00
24	COM2	884.45	490.00	54	SEG[7]	-890.55	-385.00
25	COM3	884.45	615.00	55	SEG[6]	-890.55	-510.00
26	COM4	884.45	740.00	56	SEG[5]	-890.55	-635.00
27	SEG[34]	884.45	865.00	57	SEG[4]	-890.55	-760.00
28	SEG[33]	884.45	990.00	58	SEG[3]	-890.55	-995.35

Package Information
QFP 100L Outline Dimensions

unit: inches/mm



Symbol	Dimensions in inches	Dimensions in mm
A	0.130 Max.	3.30 Max.
A1	0.004 Min.	0.10 Min.
A2	0.112 ± 0.005	2.85 ± 0.13
b	0.012 +0.004 -0.002	0.31 +0.10 -0.05
c	0.006 +0.004 -0.002	0.15 +0.10 -0.05
D	0.551 ± 0.005	14.00 ± 0.13
E	0.787 ± 0.005	20.00 ± 0.13
e	0.026 ± 0.006	0.65 ± 0.15
F	0.742 NOM.	18.85 NOM.
GD	0.693 NOM.	17.60 NOM.
GE	0.929 NOM.	23.60 NOM.
HD	0.740 ± 0.012	18.80 ± 0.31
HE	0.976 ± 0.012	24.79 ± 0.31
L	0.047 ± 0.008	1.19 ± 0.20
L1	0.095 ± 0.008	2.41 ± 0.20
y	0.006 Max.	0.15 Max.
θ	0° ~ 12°	0° ~ 12°

Notes:

1. Dimensions D&E do not include resin fins.
2. Dimensions GD & GE are for PC Board surfaces mount pad pitch
Design reference only.